

DOCKET NO.: 295958US0PCT/sal

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:

Hideo AOKI, et al.

GROUP: 1796

SERIAL NO: 10/591,455

FILED: January 18, 2007

EXAMINER: BUTTNER, D. J.

FOR: THERMOPLASTIC RESIN COMPOSITION AND MOLDED ARTICLE
COMPRISING THE SAME

SUBMISSION OF SUPPLEMENTAL APPLICATION DATA SHEET

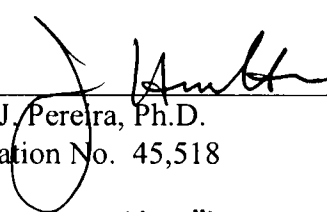
Office of Initial Patent Examination
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Applicant(s) submit herewith a Supplemental Application Data Sheet for the above-identified application for the purpose of correcting the Application date which appears incorrect on the Supplemental Application Data Sheet (Filed January 18, 2007).

Respectfully Submitted,

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